

AGILENT TECHNOLOGIES, INC.  
Legal Department, DL429  
Intellectual Property Administration  
P. O. Box 7599  
Loveland, Colorado 80537-0599

PATENT APPLICATION

ATTORNEY DOCKET NO. 10010586-1

IN THE  
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Frank S Geefay et al

Serial No.: 10/028058

Filing Date: Dec 20, 2001

Title: Wafer Level Package With Silicon Gasket



Examiner: Cruz, Lourdes C.

Group Art Unit: 2827

COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- (X) Response/Amendment ( ) Petition to extend time to respond  
(X) New fee as calculated below ( ) Supplemental Declaration  
( ) No additional fee (Address envelope to "Box Non-Fee Amendments")  
( ) Other: Petition for Ext. of time & Drwg. Transmittal (fee \$ )

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	13	MINUS	20	= 0	X \$18	\$ 0
INDEP. CLAIMS	2	MINUS	3	= 0	X \$84	\$ 0
[ ] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$280	\$ 0
EXTENSION FEE	1ST MONTH \$110.00	2ND MONTH \$410.00	3RD MONTH \$930.00	4TH MONTH \$1450.00		\$ 110
	X					
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 110

Charge \$ 110 to Deposit Account 50-1078. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 50-1078 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 50-1078 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this sheet is enclosed.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit: April 3, 2003

Typed Name: Katherine Lopez Diangson

Signature:

Respectfully submitted,

Frank S Geefay et al

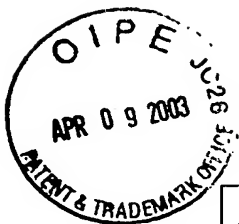
By

Judy Liao Shie

Attorney/Agent for Applicant(s)

Reg. No. 50,305

Date: April 3, 2003



<p>( x ) I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.</p> <p>Date of Deposit: <i>April 3, 2003</i> Typed Name: Katherine Lopez Diangson Signature: <i>Katherine Lopez Diangson</i></p>	<p>( ) I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on the date shown below.</p> <p>Date of Facsimile: Typed Name: Signature:</p>
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Inventor(s): Geefay, et al.**

**Examiner: Cruz, Lourdes C.**

**Serial No.: 10/028,058**

**Group Art Unit: 2827**

**Filing Date: 12/20/2001**

**Title: Wafer Level Package with Silicon Gasket**

**Amendment**

Dear Sir:

In response to the Office Action dated **17 December 2002**, having a three-month statutory period expiring **17 March 2003**, Applicants respectfully request a 1-month extension of time. Please reconsider the application in view of the following Amendments and Remarks.

**Please amend the disclosure as follows:**

**Page 2, paragraph 5**

The present invention also uses existing silicon etching technology that offers high precision in both etch depth and gasket width when carving out the desired shape. This allows greater control over the dimensions of the hermetically sealed cavity. Also, due to the high strength of silicon, the gaskets can be made narrower than in the past –